Integrated Device Technology, Inc.
6024 Silver Creek Valley Road
San Jose, CA 95138 USA

Manufacturing Bulletin

Subject: Revise MSL label contents per latest IPC/JEDEC J-STD-033B.1 (Jan-2007)

Date: March 30, 2009

Integrated Device Technology, Inc. will implement the new MSL label effective March 30, 2009. This is applicable to MSL label for levels 2, 3, 4 and 5 for all facilities.

The purpose of this change is to follow latest IPC/JEDEC J-STD-033B.1 standard. Current IDT MSL label content is per IPC/JEDEC J-STD-033B (Oct 2005).

Please refer to attachment I and II for illustration of current and new MSL label.

Changes in MSL labels:

- **Item # 3.b) From "Stored at <10% RH" revised to "Stored per J-STD-033".**
- **Item # 4.a) From "Humidity indicator card is >10% when read at 23 +/-5 deg C" revised to "Humidity indicator card reads > 10% for level 2a-5a devices or >60% for level 2 devices when read at 23 +/-5 deg C".**
- **Item # 5. From "If baking is required, devices may be baked for 48 hours at 125 +/-5 deg C" revised to "If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure".**

  The "Note" will be deleted.

Integrated Device Technology, Inc.
6024 Silver Creek Valley Road
San Jose, CA 95138 USA

Manufacturing Bulletin

Subject: Revise MSL label contents per latest IPC/JEDEC J-STD-033B.1 (Jan-2007)

Date: March 30, 2009

Affected MSL label: **English and Japanese language version**

There will be no more Japanese version of the MSL label. The new MSL label will be in English language only after the change. Please refer to Attachment II.

Yours sincerely,

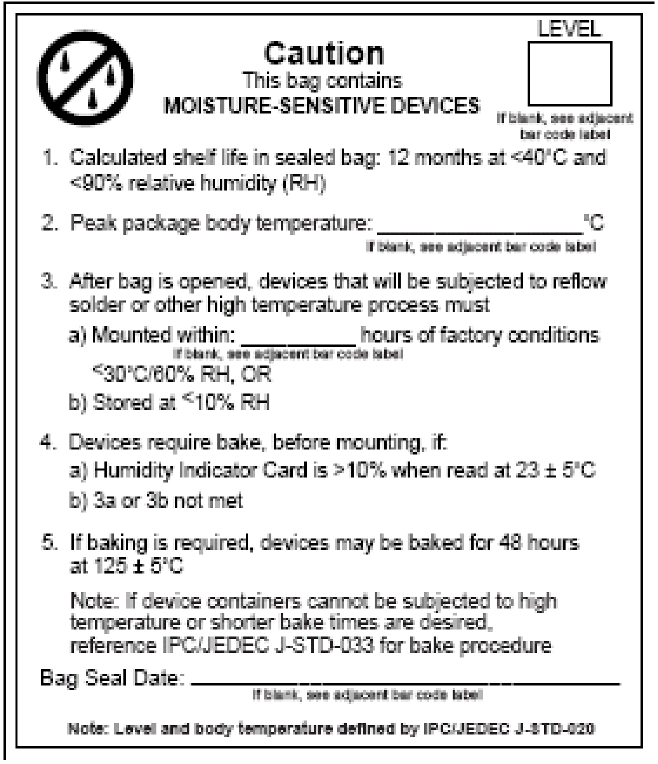
LS Koay
Manager, Product Assurance
Integrated Device Technology (Malaysia) Sdn Bhd.
lskoay@idt.com
Tel. # (604) 613-2283 (Malaysia)

Integrated Device Technology, Inc.
6024 Silver Creek Valley Road
San Jose, CA 95138 USA

Manufacturing Bulletin
Attachment I

Subject: Revise MSL label contents per latest IPC/JEDEC J-STD-033B.1 (Jan-2007)

Date: March 30, 2009



Current MSL Label

LEVEL

If blank, see adjacent bar code label

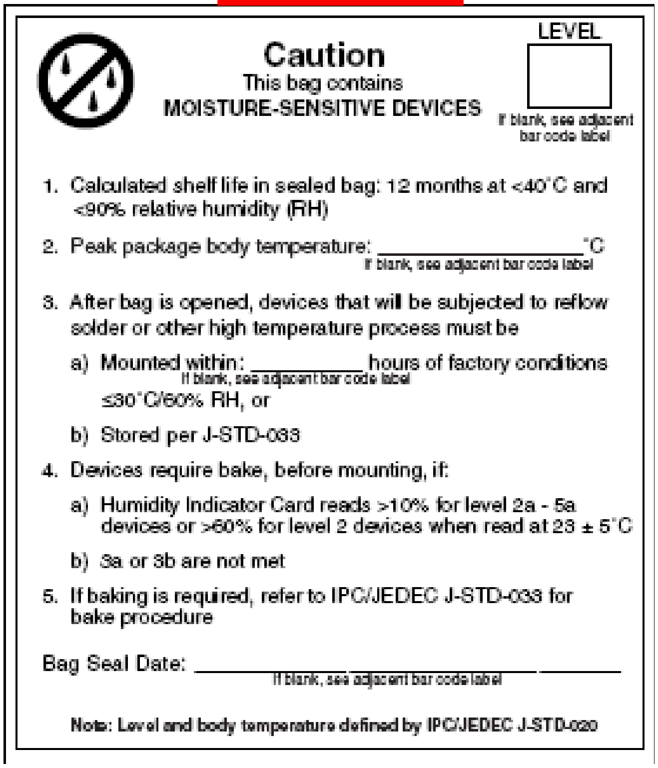
Caution
This bag contains
MOISTURE-SENSITIVE DEVICES

1. Calculated shelf life in sealed bag: 12 months at <40°C and <90% relative humidity (RH)
2. Peak package body temperature: ________________ °C
   If blank, see adjacent bar code label
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must
   a) Mounted within: __________ hours of factory conditions
   If blank, see adjacent bar code label
   <30°C/60% RH, OR
   b) Stored at <10% RH
4. Devices require bake, before mounting, if:
   a) Humidity Indicator Card is >10% when read at 23 ± 5°C
   b) 3a or 3b not met
5. If baking is required, devices may be baked for 48 hours at 125 ± 5°C

   Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure

Bag Seal Date: ______________________________
If blank, see adjacent bar code label

Note: Level and body temperature defined by IPC/JEDEC J-STD-020



New MSL Label

LEVEL

If blank, see adjacent bar code label

Caution
This bag contains
MOISTURE-SENSITIVE DEVICES

1. Calculated shelf life in sealed bag: 12 months at <40°C and <90% relative humidity (RH)
2. Peak package body temperature: ________________ °C
   If blank, see adjacent bar code label
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be
   a) Mounted within: __________ hours of factory conditions
   If blank, see adjacent bar code label
   ≤30°C/60% RH, or
   b) Stored per J-STD-033
4. Devices require bake, before mounting, if:
   a) Humidity Indicator Card reads >10% for level 2a - 5a devices or >60% for level 2 devices when read at 23 ± 5°C
   b) 3a or 3b are not met
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure

Bag Seal Date: ______________________________
If blank, see adjacent bar code label

Note: Level and body temperature defined by IPC/JEDEC J-STD-020

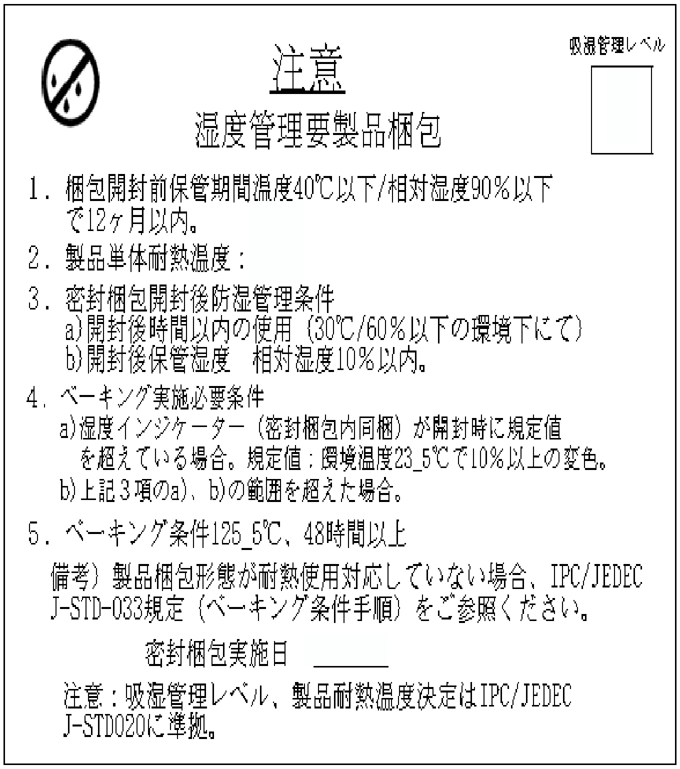
Integrated Device Technology, Inc.
6024 Silver Creek Valley Road
San Jose, CA 95138 USA

Manufacturing Bulletin
Attachment II

Subject: Revise MSL label contents per latest IPC/JEDEC J-STD-033B.1 (Jan-2007)

Date: March 30, 2009

Current MSL Label
(Japanese version)



吸湿管理レベル

注意

湿度管理要製品梱包

1．梱包開封前保管期間温度40℃以下/相対湿度90%以下で12ヶ月以内。

2．製品単体耐熱温度：

3．密封梱包開封後防湿管理条件
　a)開封後時間以内の使用（30℃/60%以下の環境下にて）
　b)開封後保管湿度　相対湿度10%以内。

4．ベーキング実施必要条件
　a)湿度インジケーター（密封梱包内同梱）が開封時に規定値を超えている場合。規定値：環境温度23_5℃で10%以上の変色。
　b)上記3項のa)、b)の範囲を超えた場合。

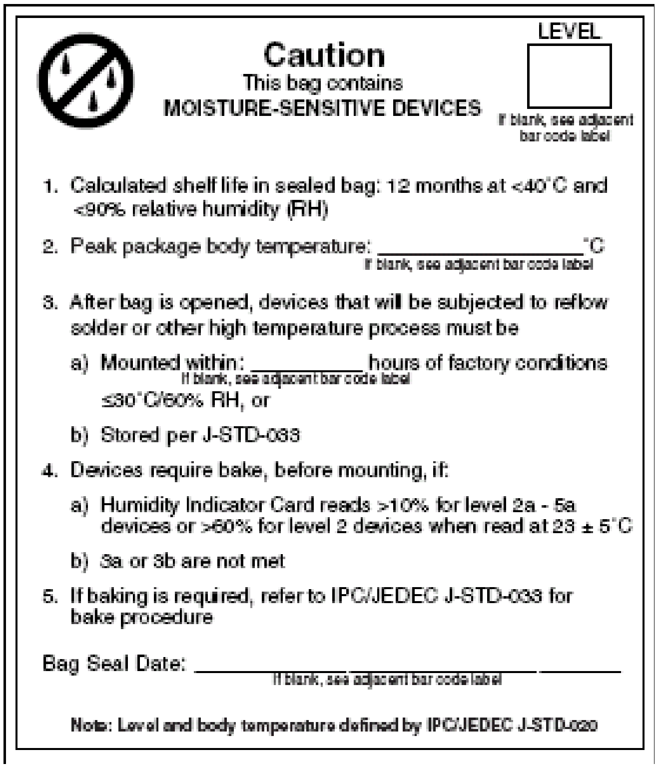
5．ベーキング条件125_5℃、48時間以上

備考）製品梱包形態が耐熱使用対応していない場合、IPC/JEDEC J-STD-033規定（ベーキング条件手順）をご参照ください。

密封梱包実施日 ______

注意：吸湿管理レベル、製品耐熱温度決定はIPC/JEDEC J-STD020に準拠。

New MSL Label
(English version)



LEVEL

If blank, see adjacent bar code label

Caution

This bag contains

MOISTURE-SENSITIVE DEVICES

1. Calculated shelf life in sealed bag: 12 months at <40°C and <90% relative humidity (RH)
2. Peak package body temperature: ________________°C
   If blank, see adjacent bar code label
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be
   a) Mounted within: _________ hours of factory conditions
      If blank, see adjacent bar code label
      ≤30°C/60% RH, or
   b) Stored per J-STD-033
4. Devices require bake, before mounting, if:
   a) Humidity Indicator Card reads >10% for level 2a - 5a devices or >60% for level 2 devices when read at 23 ± 5°C
   b) 3a or 3b are not met
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure

Bag Seal Date: ________________________
If blank, see adjacent bar code label

Note: Level and body temperature defined by IPC/JEDEC J-STD-020